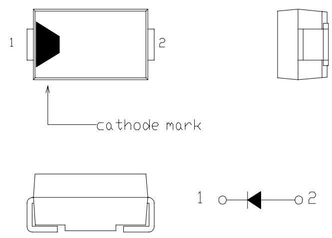
Nihon Inter Electronics Corporation

SBD Type : EC31QS10

FEATURES

OUTLINE DRAWING



- * Miniature Size,Surface Mount Device
- * Low Forward Voltage Drop
- * Low Power Loss,High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

Maximum Ratings

Approx Net Weight:0.06g

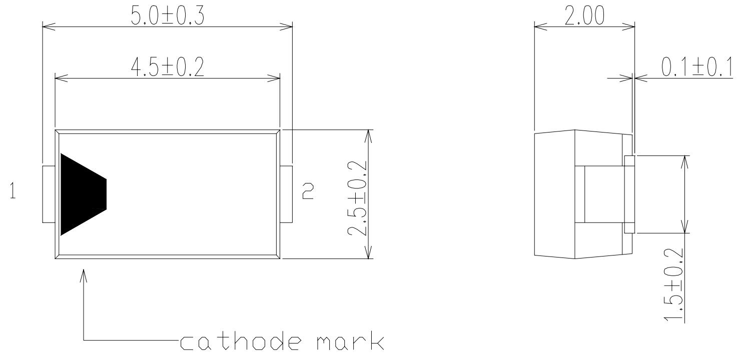
Rating	Symbol	EC31QS10			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	100			V
Average Rectified Output Current	I_O	1.3	Ta=26 ℃ *1	50Hz Half Sine Wave Resistive Load	A
		3.0	Tl=84 ℃ Tl:Lead Temperature		
RMS Forward Current	$I_{F(RMS)}$	4.71			A
Surge Forward Current	I_{FSM}	60	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T_{jw}	-40 to +150			℃
Storage Temperature Range	T_{stg}	-40 to +150			℃

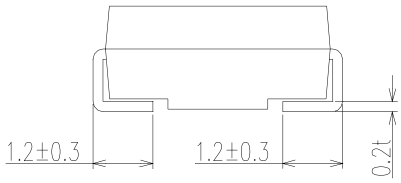
Electrical • Thermal Characteristics

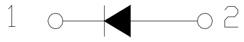
Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	Tj= 25℃, V_{RM}= V_{RRM}	-	-	2	mA
Peak Forward Voltage		V_{FM}	Tj= 25℃, I_{FM}= 3.0A	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$Rth_{(j-a)}$	*1	-	-	108	℃ /W
	Junction to Lead	$Rth_{(j-l)}$	-	-	-	23	

*1 Alumina Substrate Mounted
Soldering Lands=2x2mm,Both Sides

EC31QS10 OUTLINE DRAWING (Dimensions in mm)







SOLDERING PAD